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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

1002 U.S. PTO
10/085183

02/27/02

APPL NUM 10085183	FILING DATE 02/27/2002	CLASS 257	SUBCLASS 712	GAU 2815	EXAMINER <i>Goldie Lee</i>
**APPLICANTS: Zheng Wen-Chun; Jung Henry; <i>Chw</i>					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 03226.111001;P6259	
TITLE : Solid assembly of flip-chip package attached to heat removal device and method of manufacturing same					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAMER		PREPARED FOR ISSUE	
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